

+ Handling Instructions

EE895 Miniature Sensor Module for CO₂, Temperature and Barometric Pressure



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in sensor
technology.

PLEASE NOTE

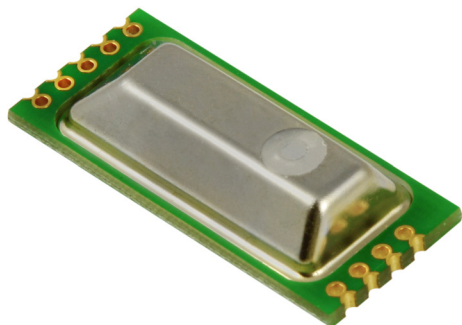
Find this document and further product information on our website at www.epluse.com/ee895.

Overview

This document provides general handling recommendations for transport, storage and assembly of the EE895.

The miniature sensor module is a measuring element for CO₂, temperature and barometric pressure. Due to the delicacy of the sensor, special care in handling must be taken during assembly and further transport.

The physical properties of the miniature sensor module can change due to mechanical or thermal loads, high acceleration or mechanical shock. This can affect the factory calibrations and lead to incorrect measurements. In extreme cases, the module may be damaged.



EE895 - Module



EE895 - 100 pcs. tray packaging

Storage Conditions

Please observe the following ambient conditions for storage:

Temperature: -40...+60 °C (-40...+140 °F)
Humidity: 0...95 %RH (non-condensing)
Pressure: 700...1 100 mbar (10...20 psi)

Moisture Sensitivity Level Rate

The EE895 is not intended for reflow soldering and therefore does not feature a moisture sensitivity level rate (MSL). Nevertheless, it should be considered compatible with MSL 1 in terms of storage and handling.

ESD Protection



ESD (electrostatic discharge) precautions must be observed while manually soldering the EE895.

The EE895 can be mounted facing either upwards or downwards.

Further details on hand soldering in the variants solder pads or plated contacts are described in the “Mounting Recommendation” section of the User Manual.

Mechanical Stress

During Transportation

When removing the product from its original packaging and internal transport container, take special care to avoid strong acceleration or mechanical shocks. Acceleration caused by impact with the ground, for example, can lead to inaccurate measurement results. Please follow the existing product packaging guidelines for electronics. This includes paying special attention to the internal padding, guidelines for product positioning and sealing the packaging.

During Mounting

Avoid touching the metal enclosure. It is better to handle the module by the edges of the electronics board. The EE895 enclosure and the circuit board shall not be exposed to unnecessary mechanical stress during installation and mounting.

PLEASE NOTE

The sensor module is equipped with a fine dust filter to protect the sensing module. If the EE895 is used in a device designed for harsh environments, the device must be equipped with a filter as well.